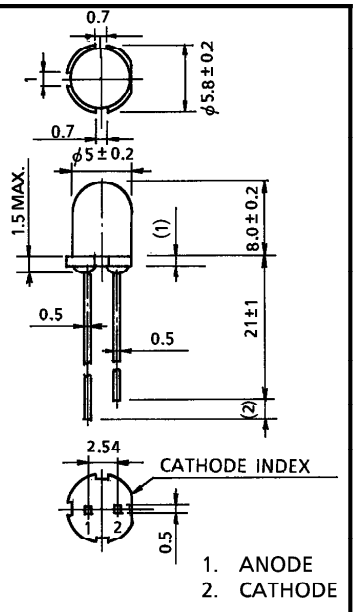
TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

TLGD135AP

PANEL CIRCUIT INDICATOR

Unit in mm



JEDEC	—
EIAJ	—
TOSHIBA	4-5V4

Weight : 0.33g

- All Plastic Mold Type

  Clear Transparent Lens
- High Intensity & Moderate Radiation Angle

  Half Angle = ±15 deg. (Typ.) (limits for 50% of I_V)

  Recommended Forward Current : I_F = 15~20mA (DC)
- Fast Response Time, Capable of Pulse Operation.
- Without stand-offs

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	I_F	40	mA
Reverse Voltage	V_R	4	V
Power Dissipation	P_D	120	mW
Operating Temperature Range	T_{opr}	−20~85	°C
Storage Temperature Range	T_{stg}	−30~100	°C

ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage		V_F	I_F = 20mA	—	2.15	2.8	V
Reverse Current		I_R	V_R = 4V	—	—	5	μA
Luminous Intensity	TLGD135AP	I_V	I_F = 20mA (Note)	153	300	—	mcd
	TLGD135AP (PQ)			153	—	736	
Peak Emission Wave Length		λ_p	I_F = 20mA	—	567	—	nm
Spectral Line Half Width		$\Delta\lambda$	I_F = 20mA	—	25	—	nm

(Note) Rank selection carried out under next standard range respectively, although it needs ±15% sdditionary for guaranteed limits.

P : 180-360mcd Q : 320-640mcd

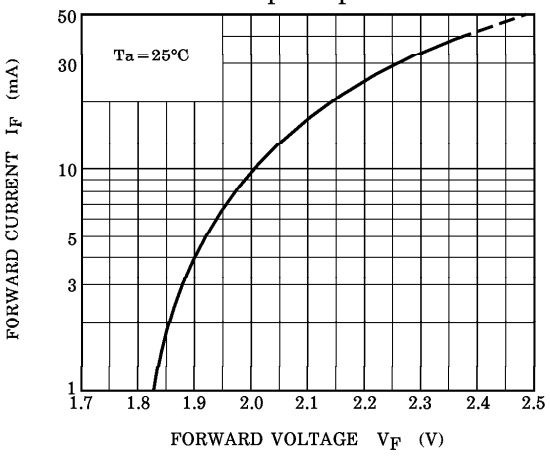
Each rank products is classified by package unit, and (PQ) includes P and Q.

PRECAUTION

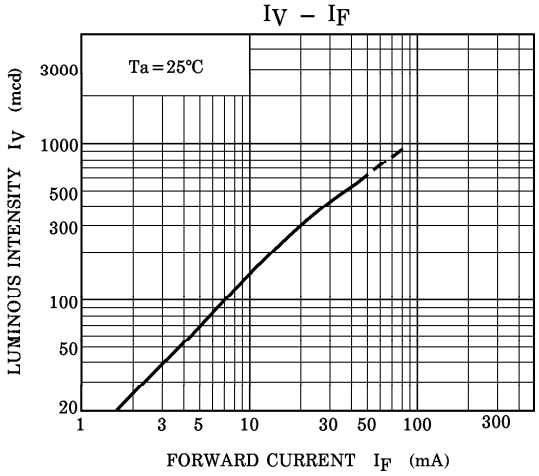
Please be careful of the followings.

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
  (Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.

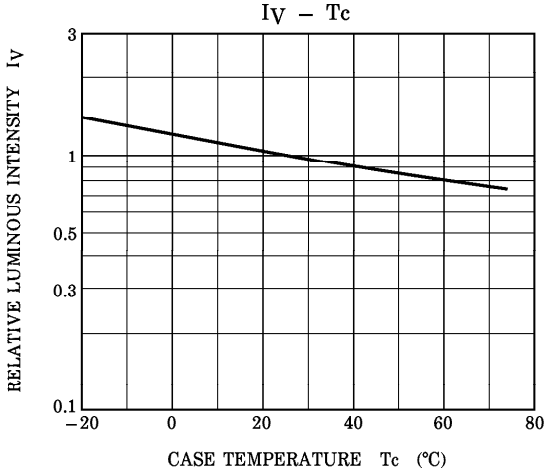
$I_F - V_F$



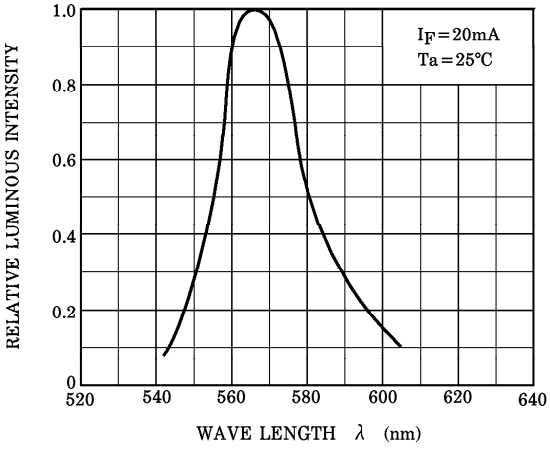
$I_V - I_F$



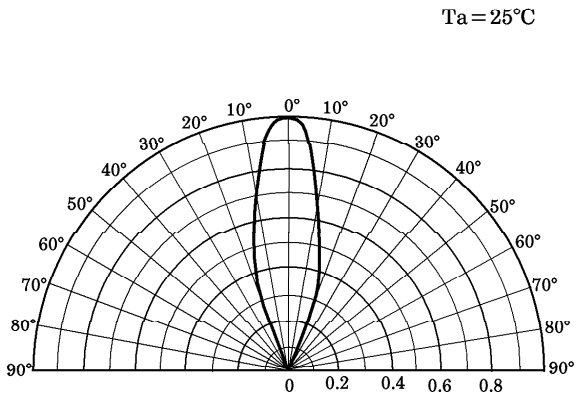
$I_V - Tc$



RELATIVE LUMINOUS INTENSITY – WAVE LENGTH



RADIATION PATTERN



$I_F - Ta$